



Removing charges after drying wafer

OUTLINE / PREVIOUS

Customer: Semiconductor equipment manufacturer

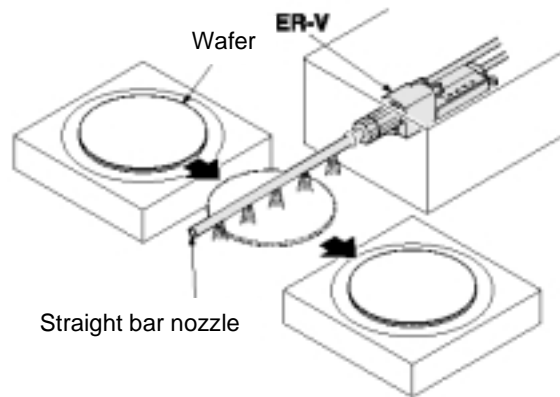
Process: Wafer process, from cleaning to drying

Static is to be removed when wafer is dried after cleaning.

PROBLEM

Static remover is required which can be safely used under water droplet environment.

SOLUTION



MODEL / HOW TO

ER-VS01 ER-VAB032

Install main unit **ER-VS01** away from water droplet, and attach optional straight bar nozzle **ER-VAB032**, to ensure safety.

BENEFIT 1 Straight bar nozzle

We have optional straight bar nozzle for **ER-V**, which enables safe static removal even in a water droplet environment. Effective charge removal length is as below.

ER-VAB032: 320 mm, ER-VAB065: 650 mm

BENEFIT 2 Compact in size

ER-VS01 is as compact as W109 x H28 x D27 mm, which enables easier installation even in additional one. Also, the high-voltage power supply unit is incorporated in the main unit, which requires no extra space except static removal part.

BENEFIT 3 Low power consumption and low-voltage wiring

Power consumption is only 70mA in power supply voltage of 24V DC. No high-voltage cables are required, which ensures safety.

